7-SEGMEN

12



Data sheet acquired from Harris Semiconductor SCHS072B – Revised July 2003

CMOS BCD-to-7-Segment Latch Decoder Drivers

High-Voltage Types (20-Volt Rating)





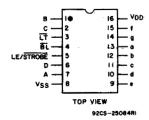
200 - 25097

CD4511B types are BCD-to-7-segment latch decoder drivers constructed with CMOS logic and n-p-n bipolar transistor output devices on a single monolithic structure. These devices combine the low quiescent power dissipation and high noise immunity features of RCA CMOS with n-p-n bipolar output transistors capable of sourcing up to 25 mA. This capability allows the CD4511B types to drive LED's and other displays directly.

Lamp Test (LT), Blanking (BL), and Latch Enable or Strobe inputs are provided to test the display, shut off or intensity-modulate it, and store or strobe a BCD code, respectively. Several different signals may be multiplexed and displayed when external multiplexing circuitry is used.

The CD4511B types are supplied in 16-lead hermetic dual-in-line ceramic packages (F3A suffix), 16-lead dual-in-line plastic packages (E suffix), 16-lead small-outline packages (NSR suffix), and 16-lead thin shrink small-outline packages (PW and PWR suffixes).

These devices are similar to the type MC14511.



CD4511B TERMINAL ASSIGNMENT

Features:

- High-output-sourcing capability up to 25 mA
- Input latches for BCD Code storage
- Lamp Test and Blanking capability
- 7-segment outputs blanked for BCD input codes > 1001
- 100% tested for quiescent current at 20 V
- Max. input current of 1 μA at 18 V, over full package-temperature range, 100 nA at 18 V and 25°C
- 5-V, 10-V, and 15-V parametric ratings

Applications:

Driving common-cathode LED displays

V_{SS}=8 V_{DD}=16

FUNCTIONAL DIAGRAM

- Multiplexing with common-cathode LED displays
- Driving incandescent displays

CD4511B Types

■ Driving low-voltage fluorescent displays

MAXIMUM RATINGS, Absolute-Maximum Values: DC SUPPLY-VOLTAGE RANGE, (VDD) Voltages referenced to VSS Terminal) -0.5V to +20V INPUT VOLTAGE RANGE, ALL INPUTS -0.5V to VDD +0.5V DC INPUT CURRENT, ANY ONE INPUT ±10mA POWER DISSIPATION PER PACKAGE (PD): For TA = -55°C to +100°C For TA = +100°C to +125°C Derate Linearity at 12mW/°C to 200mW DEVICE DISSIPATION PER OUTPUT TRANSISTOR FOR TA = FULL PACKAGE-TEMPERATURE RANGE (All Package Types) 100mW OPERATING-TEMPERATURE RANGE (Tatg) STORAGE TEMPERATURE (Tatg) At distance 1/16 ± 1/32 inch (1.59 ± 0.79mm) from case for 10s max +265°C

OPERATING CONDITIONS AT TA = 25°C Unless Otherwise Specified

For maximum reliability, nominal operating conditions should be selected so that operation is always within the following ranges

Characteristic	V _{DD}	Min.	Max.	Units
Supply Voltage Range (T _A): (Full Package-Temperature Range)	-	3	18	٧
	5	150	-	ns
Set-Up Time (t _S)	10	70	_	ns
	15	40		ns
	5	0	_	ns
Hold Time (tH)	10	0		ns
	15	0	-	ns
	5	400	_	ns
Strobe Pulse Width (t _W)	10	160		ns
Hold Time (t _H)	15	100	_	ns

CD4511B Types

STATIC ELECTRICAL CHARACTERISTICS

	TE	ST CON	DITIO	NS	LIMITS AT INDICATED TEMPERATURES (°C)								
					LI	IMITS AT	r indiça	ATED TE	EMPER#	TURES	(oc)		
CHARACTERISTIC	ІОН	v _o	VIN	V _{DD}		ſ	Γ		Ι	+25	•	Units	
	(mA)	(V)	(V)	(V)	-55	-40	+85	+125	Min.	Тур.	Max.		
Quiescent Device	<u> </u>	_	_	5	5	5	150	150	_	0.04	5		
Current: IDD			_	10	10	10	300	300	_	0.04	10	μА	
Max,			_	15	20	20	600	600		0.04	20	۳.	
			_	20	100	100	3000	3000	-	0.08	100		
Output Voltage:				_			0.05						
Law Lavel Ma	-		0,5	5 10			0.05 0.05		· -	0	0.05	١,,	
Low-Level VOL Max.		<u> </u>	0,10	15			0.05		-	0	0.05	: V	
IVIGA.	<u> </u>	<u> </u>							<u> </u>		0.05.	<u> </u>	
112-6-1	<u> </u>	-	0,5	5	4	4	4.2	4.2	4.1	4.55	<u> </u>	l	
High-Level V _{OH}	_	-	0,10	10 15	9	9	9.2	9.2	9.1	9.55		٧	
Min.			0.15	15	14	14	14.2.	14.2	14.1	14.55	-	ļ	
Input Low	_	0.5,3.8		5			1.5			_	1.5		
Voltage, VIL	_	1,8.8	-	10			3		-		3	v	
Max.		1.5,13.8		15			4		-	_	4		
Input High	-	0.5,3.8		5			3.5		3.5	-	_		
Voltage, V _{IH}		1,8.8		10			7	7	_	_	1 v		
Min.		1.5,13.8		15			11		11		-	<u>l</u>	
	0			4	4.0	4.0	4.20	4.20	4.10	4.55			
	5	-							_	4.25			
	10			5	3.80	3.80	3.90	3.90	3.90	4.10	_	v	
	15		-			-	3.50	3.50		3.95	_	-	
	20	-			3.55	3.55	3.30	-	3.40	3.75			
	25				3.40	3.40	-		3.10	3.55	~	~	
	0			•	9.0	9.0	9.20	9.20	9.10	9.55			
Output Drive	5					-	-		_	9.25	-		
Voltage:	10	-	-		8.85	8.85	9.00	9.00	9.00	9.15		v	
High Level VOH	15	_	-	10			-		-	9.05			
Min.	20	-	-		8.70	8.70	8.40	8.40	8.60	8.90			
	25	-	_		8.60	8.60	_		8.30	8.75	_		
	0			🕈	14.0	14.0	14.20	14.20	14.10	14.55			
ļ	5				-	-	-	-		14.30			
	10			15	13.90	13.90	14.0	14.0	14.0	14.20		V	
	15 20				13.75	12.75	13.50	1250	12.70	14.10			
j	25		-]	13.75	13.75 13.65	13.50	13.50	13.70 13.50	13.95 13.80	-		
	25				13.05	13.05		_	13.50	13.60			
Output Low								,					
(Sink) Current,	_	0.4	0,5	5	0.64	0.61	0.42	0.36	0.51	1	_		
OL.		0.5	0,10	10	1.6	1.5	1.1	0.9	1.3	2.6		mΑ	
Min.	_	1.5	0,15	15	4.2	4	2.8	2.4	3.4	6.8			
Input Current, I _{IN} Max.	-	0,18	0,18	18	±0.1	±0.1	±1	±1	-	±10-5	±0.1	μΑ	

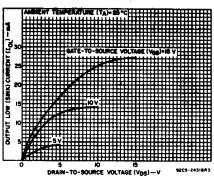


Fig. 1 — Typical output low (sink) current characteristics.

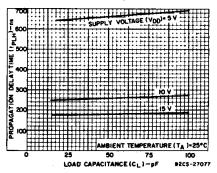


Fig. 2 — Typical data-to-output, low-to-high-level propagation dalay time as a function of load capacitance.

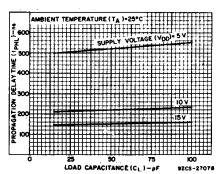


Fig. 3 — Typical data-to-output, high-to-low-level propagation delay time as a function of load capacitance.

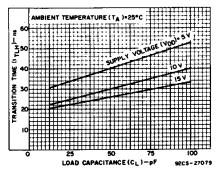


Fig. 4 — Typical low-to-high-level transition time as a function of load capacitance.

CD4511B Types

DYNAMIC ELECTRICAL CHARACTERISTICS at $T_A = 25^{\circ}C$, Input t_r , $t_f = 20$ ns, C_L = 50 pF, R_L = 200 k Ω

CHARACTERISTIC	Test Conditions	A	LIMITS All Package		UNITS
X	Y _{DD} Volts	Min.	Тур.	Max.	
Propagation Delay Time:	5	_	520	1040	
(Data)	10	_	210	420	ns
High-to-Low Level, tpHL	15	-	150	300	
	5	_	660	1320	
Low-to-High Level, tPLH	10	l –	260	520	ns
	15	_	180	360	<u> </u>
Propagation Delay Time:	5	_	350	700	
(BL)	10	-	175	350	ns
High-to-Low Level, tpHL	15	_	125	250	
	5		400	800	
> Low-to-High Level, tpLH	10	_	175	350	ns
	15	- ,	150	300	
Propagation Delay Time:	5	-	250	500	
(LT)	10	-	125	250	ns
High-to-Low Level, tpHL	15		85	170	
	5	_	150	300	
Low-to-High Level, tPLH	10	_	75	150	ns
	15	_	50	100	
Transition Time:	. 5	_	40	80	
	10	-	30	60	пs
Low-to-High Level, tTLH	15		25	50	٠
	5	-	125	310	
	10	_	75	185	ns
High-to-Low Level, tTHL	15	_	65	160	
Minimum Co. Ha Ti	5	150	75	_	
Minimum Set-Up Time, t _S	10	70	35	-	ns
	15	40	20	_	
	5	0	-75	_	
Minimum Hold Time, tH	10	0	-35	_	ns
	15	0	-20	_	
6. I B. W	5	400	200	_	
Strobe Pulse Width, t _W	10	160	80	. —	ns
	15	100	50		
Input Capacitance, CIN			5	7.5	pF

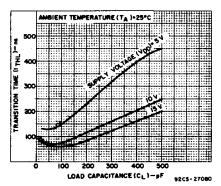


Fig. 5 - Typical high-to-low transition time as a function of load capacitance.

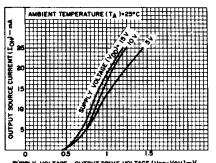


Fig. 6 - Typical voltage drop (V_{DD} to output) vs. output source current as a function of supply.

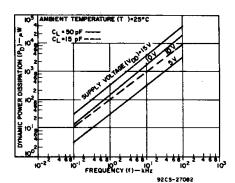
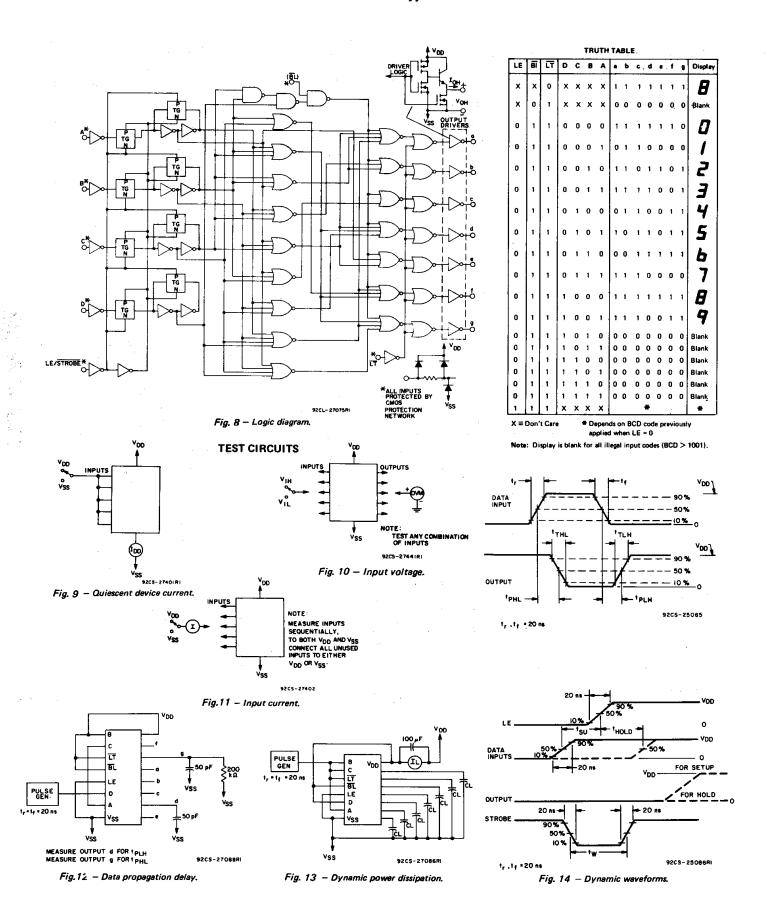
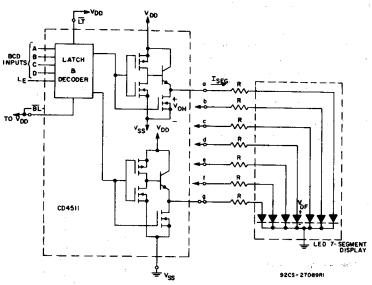


Fig. 7 - Typical dynamic power dissipation characteristics.

CD4511B Types



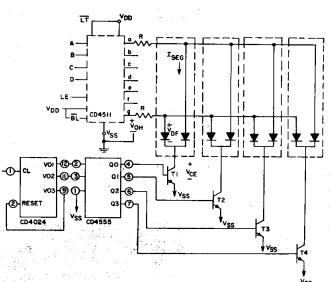
APPLICATIONS Interfacing with Various Displays



Duty Cycle = 100%

ISEG = IDIODEAVG. = 20 mA at Luminous Intensity/Segment = 250 microcandles

Fig. 15 - Driving common-cathode 7-segment LED displays (example Hewlet-Packard 5082-7740).



Multiplexing Scheme Showing 2 of 7 Segments Connected

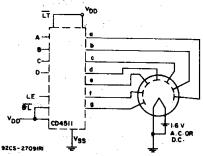
Transistors T₁-T₄ (RCA-2N3053 or 2N2102) have I_C Max.rating >7xI_{SEG}

Duty Cycle = 25% I SEG = $^{[I]}$ DIODE_{AVG} I × 4 $_{R}$ = $^{(V}$ OH - V DF - V CE I

ISEG

All unused inputs on CD4555 are connected to V_{DD} or V_{SS}

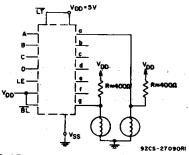
Fig. 18 — Multiplexing with common-cathode 7-segment LED displays (example Hewlet-Packard 5082-7404 4 character display or 4 discrete Monosanto Man 3 displays).



A medium-brightness intensity display can be obtained with low-voltage fluorescent displays such as the Tung-Sol Digivac S/G** Series.

**Trademark Tung-Sol Division Wagner Electric Co.

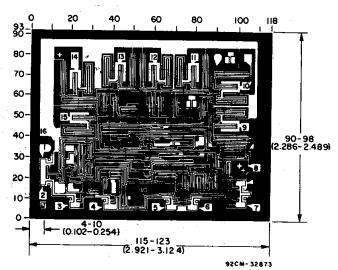
Fig. 16 — Driving low-voltage fluorescent displays.



2 of 7 Segments Shown Connected

Resistors R from V_{DD} to each 7-segment driver output are chosen to keep all Numitron segments slightly on and warm.

Fig. 17 — Driving incandescent displays (RCA Numitron DR2000 series displays).



Dimensions and pad layout for CD45118 chip.

Dimensions in parentheses are in millimeters and are derived from the basic inch dimensions as indicated. Grid graduations are in mils (10^{-3}) inch).





11-Apr-2013

PACKAGING INFORMATION

Orderable Device	Status	Package Type	•	Pins	_	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Top-Side Markings	Samples
	(1)		Drawing		Qty	(2)		(3)		(4)	
CD4511BE	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-55 to 125	CD4511BE	Samples
CD4511BEE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-55 to 125	CD4511BE	Samples
CD4511BF	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	CD4511BF	Samples
CD4511BF3A	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	CD4511BF3A	Samples
CD4511BNSR	ACTIVE	so	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	CD4511B	Samples
CD4511BNSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	CD4511B	Samples
CD4511BNSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	CD4511B	Samples
CD4511BPW	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	CM511B	Samples
CD4511BPWE4	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	CM511B	Samples
CD4511BPWG4	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	CM511B	Samples
CD4511BPWR	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	CM511B	Samples
CD4511BPWRE4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	CM511B	Samples
CD4511BPWRG4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	CM511B	Samples

⁽¹⁾ The marketing status values are defined as follows: **ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.



PACKAGE OPTION ADDENDUM

11-Apr-2013

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes. **Pb-Free** (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) Multiple Top-Side Markings will be inside parentheses. Only one Top-Side Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Top-Side Marking for that device.

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PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CD4511BPWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

www.ti.com 8-Apr-2013



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)	
CD4511BPWR	TSSOP	PW	16	2000	367.0	367.0	35.0	

14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



PW (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M—1994.
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
- E. Falls within JEDEC MO-153



PW (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



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